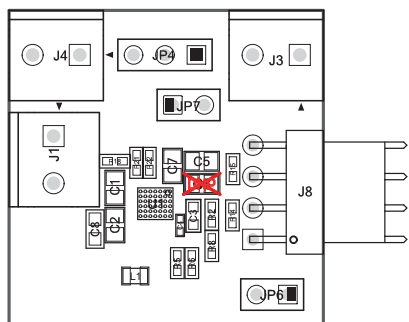


- Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.
- These assemblies are ESD sensitive, ESD precautions shall be observed.
- These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-03042	REV: E1	SVN REV: Not In VersionControl
TOP ASSEMBLY DRAWING	TID #: A0867987		
PLOT NAME = Top Assembly Drawing	GENERATED : 12/23/2016 3:09:44 PM	TEXAS INSTRUMENTS	

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